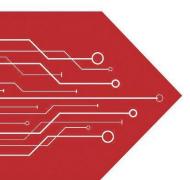
MSKSEMI















ESD

TVS

TSS

MOV

GDT

PLED

Product data sheet

www.msksemi.com

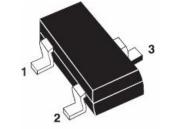


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Features

- 2 Unidirectional Transil functions
- Low leakage current: I_{RM} max< 1 µA at V_{RM}
- 300W peak pulse power(8/20µs)



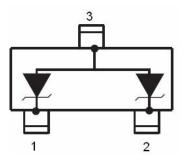
Complies with the following standards IEC61000-4-2

Level 4 15 kV (air discharge) 8 kV(contact discharge) MIL STD 883E - Method 3015-7 Class 3 25 kV HBM (Human Body Model)

Applications

- Computers
- **Printers**
- Communication systems

It is particularly recommended for the RS232 I/O port protection where the line interface withstands only with 2kV ESD surges.



SOT-23

Electrical Characteristics

	V _{BR} @		I _R	I _{RM} @ V _{RM}		Rd	αΤ	С	V _F @ I _F	
P/N	min.	max.		max.		typ.	max.	typ.	max.	
						note 1	note 2	0V bias		
	V	V	mA	μΑ	V	mΩ	10 ⁻⁴ /⊃C	pF	V	mA
ESDA5V3L-MS	5.3	5.9	1	2	3	280	5	220	1.25	200
ESDA6V1L-MS	6.1	7.2	1	20	5.25	350	6	140	1.25	200
ESDA14V2L-MS	14.2	15.8	1	5	12	650	10	90	1.25	200
ESDA25L-MS	25	30	1	1	24	1000	10	50	1.2	10

note 1 : Square pulse lpp = 15A, tp= $2.5\mu s$. **note 2**: \triangle VBR = α T* (Tamb -25°C) * VBR (25°C)

Absolute Ratings (T_{amb}=25°C)

Symbol	Parameter	Value	Units	
P _{PP}	Peak Pulse Power (t _p = 8/20μs)	300	W	
TL	Maximum lead temperature for soldering during 10s	260	°C	
T _{stg}	Storage Temperature Range	-55 to +155	°C	
T _{op}	Operating Temperature Range	-40 to +125	°C	
Tj	Maximum junction temperature	150	°C	
	Electrostatic discharge			
V _{PP}	MIL STD 883C -Method 3015-6	25	kV	
	IEC61000-4-2 air discharge	15	KV	
	IEC61000-4-2 contact discharge	8		



Electrical Parameter

Symbol	Parameter
I _{PP}	Maximum Reverse Peak Pulse Current
Vc	Clamping Voltage @ IPP
V _{RWM}	Working Peak Reverse Voltage
I _R	Maximum Reverse Leakage Current @ V _{RWM}
I _T	Test Current
V_{BR}	Breakdown Voltage @ I⊤

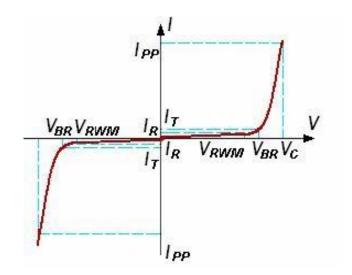


FIG1: Pulse Waveform

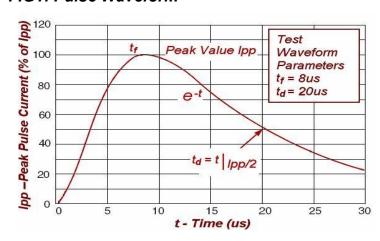
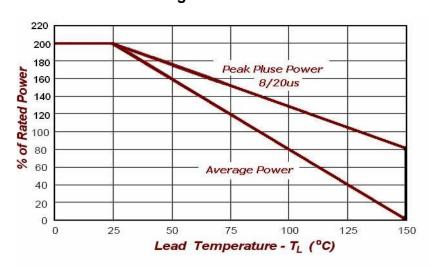


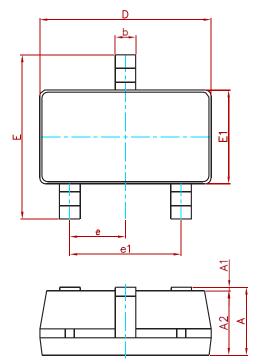
FIG2:Power Derating

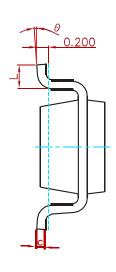


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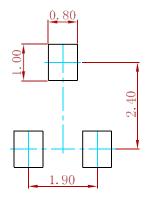
PACKAGE MECHANICAL DATA





Symbol	Dimensions I	n Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.300	0.500	0.012	0.020	
С	0.100	0.200	0.004	0.008	
D	2.820	3.020	0.111	0.119	
E1	1.500	1.700	0.059	0.067	
Е	2.650	2.950	0.104	0.116	
е	0.950(BSC)		0.037(BSC)		
e1	1.800	2.000	0.071	0.079	
L	0.300	0.600	0.012	0.024	
0	0°	8°	0°	8°	

Suggested Pad Layout



Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
ESDAXXXL-MS	SOT-23	3000



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